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**Amendments to the Claims**

Applicants respectfully request that Examiner consider entry of the following amendments, which Applicants believe will put the claims in condition for allowance. Please amend the claims as follows to clarify the patentably distinguishable elements of the instant invention:

1. (Currently Amended) A method of forming a hole in a board, comprising the steps of:
  - (a) irradiating a laser beam on a surface of a lens, wherein the laser beam contacts the lens in a first position such that the laser irradiates said board from a direction perpendicular thereto to thereby drill a hole in said board;
  - (b) irradiating a laser beam onto the lens wherein the laser beam contacts the lens in a second position such that the laser irradiates said hole from a direction inclined at a predetermined angle relative to said perpendicular direction; and
  - (c) repeating the step (b) until diameters of a top portion and a bottom portion of said hole become substantially equal to each other and the sides of said hole are substantially parallel.
2. (Original) The method according to claim 1, wherein said predetermined angle is selected within the range of from about 2 to 5 degrees measured from a perpendicular direction relative to said board.
3. (Currently Amended) A method of forming a plurality of holes in a board, comprising the steps of:
  - (a) irradiating a laser beam on a surface of a lens, wherein the laser beam contacts the lens in a plurality of positions such that the laser irradiates said board from a direction perpendicular thereto in a plurality of predetermined hole positions thereof in turn to thereby drill a plurality of holes in said board;
  - (b) irradiating a laser beam onto the lens, wherein the laser beam contacts the lens in a plurality of positions such that the laser irradiates the plurality of holes drilled in said plurality of predetermined hole positions in turn from a direction inclined at a predetermined angle relative

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to said perpendicular direction; and

(c) repeating the step (b) until diameters of a top portion and a bottom portion of each of said holes become substantially equal to each other and the sides of each of said holes are substantially parallel.

4. (Original) The method according to claim 3, wherein said predetermined angle is selected within the range of from about 2 to 5 degrees measured from a perpendicular direction relative to said board.

5. (Currently Ammended) The method according to claim 4, wherein the step (c) repeating the step (b) includes a step of irradiating a laser beam while changing a laser beam irradiation position along a circumferential direction of each of said holes using a first and second galvano mirror to change the location through the laser beam passes through the lens.

6. (Currently Amended) A method of forming a plurality of holes in a board, comprising the steps of:

(a) irradiating a laser beam on a surface of a lens, wherein the laser beam contacts the lens in a plurality of positions such that the laser irradiates said board from a direction inclined at a predetermined angle relative to a direction perpendicular to the surface of said board, in a plurality of predetermined hole positions of said board in turn to thereby drill a plurality of holes in said board; and

(b) repeating the step (a) until diameters of a top portion and a bottom portion of each of said holes become substantially equal to each other and the sides of each of said holes are substantially parallel.

7. (Original) The method according to claim 6, wherein said predetermined angle is selected within the range of from about 2 to 5 degrees measured from a perpendicular direction relative

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to said board.

8. (Currently Amended) The method according to claim 7, wherein the step (b) repeating the step (a) includes a step of irradiating a laser beam while changing a laser beam irradiation position along a circumferential direction of each of said holes using a first and second galvano mirror.

9. (Currently Amended) A hole drilling apparatus comprising:

an oscillator producing a laser beam for drilling a hole in a board;

at least one collimator lens;

an angle adjustment device;

a condenser lens through which the laser beam passes and which determines an angle of the laser beam relative to said board depending on a laser beam passing position of said lens;

a galvano mirror adapted to change ~~changing~~ the laser beam passing position of said lens depending on the number of times of laser beam irradiation to said board;

a mask having the ability to change the diameter of the laser beam to be equal to or less than the diameter of a desired hole diameter; and

a moveable stage to which the board is coupled having the capability to adjust the position of the board with respect to the laser beam;

wherein the laser beam passes through the collimator lens and the mask such that the laser beam has a predetermined diameter, the laser beam is then reflected from the galvano mirror, which is adjusted by the angle adjustment device, through the condenser lens and irradiates the board.

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10. (Currently Amended) The hole drilling apparatus according to claim 9, wherein an angle of said ~~mirror~~ condenser lens is adjustable for changing the laser beam passing position of said lens.

11. (Canceled)